

Photocouplers Infrared LED & Photo Darlington Transistor

# TLP627M, TLP627MF

## 1. Applications

- Programmable Logic Controllers (PLCs)
- I/O Interface Boards
- Home Electric Appliances

## 2. General

TLP627M is a photocoupler that consists of an infrared emitting diode optically coupled to a photo darlington transistor. Housed in a 4pin DIP, it has a high noise immunity and high insulation. With the high breakdown voltage between the collector and emitter, TLP627M is suitable in applications such as 100 V DC output modules of programmable controllers.

TLP627MF is a lead forming type for the long creepage mounting of TLP627M.

## 3. Features

- (1) Collector-emitter voltage: 300 V (min)
- (2) Current transfer ratio: 1000 % (min) (@ $I_F = 1$  mA,  $V_{CE} = 1$  V)
- (3) Isolation voltage: 5000 Vrms (min)
- (4) Operating temperature: -55 to 110 °C
- (5) Safety standards

UL-recognized: UL 1577, File No.E67349

cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN 60747-5-5, EN 62368-1 (**Note 1**)

CQC-approved: GB4943.1, GB8898 Japan Factory (Pending)

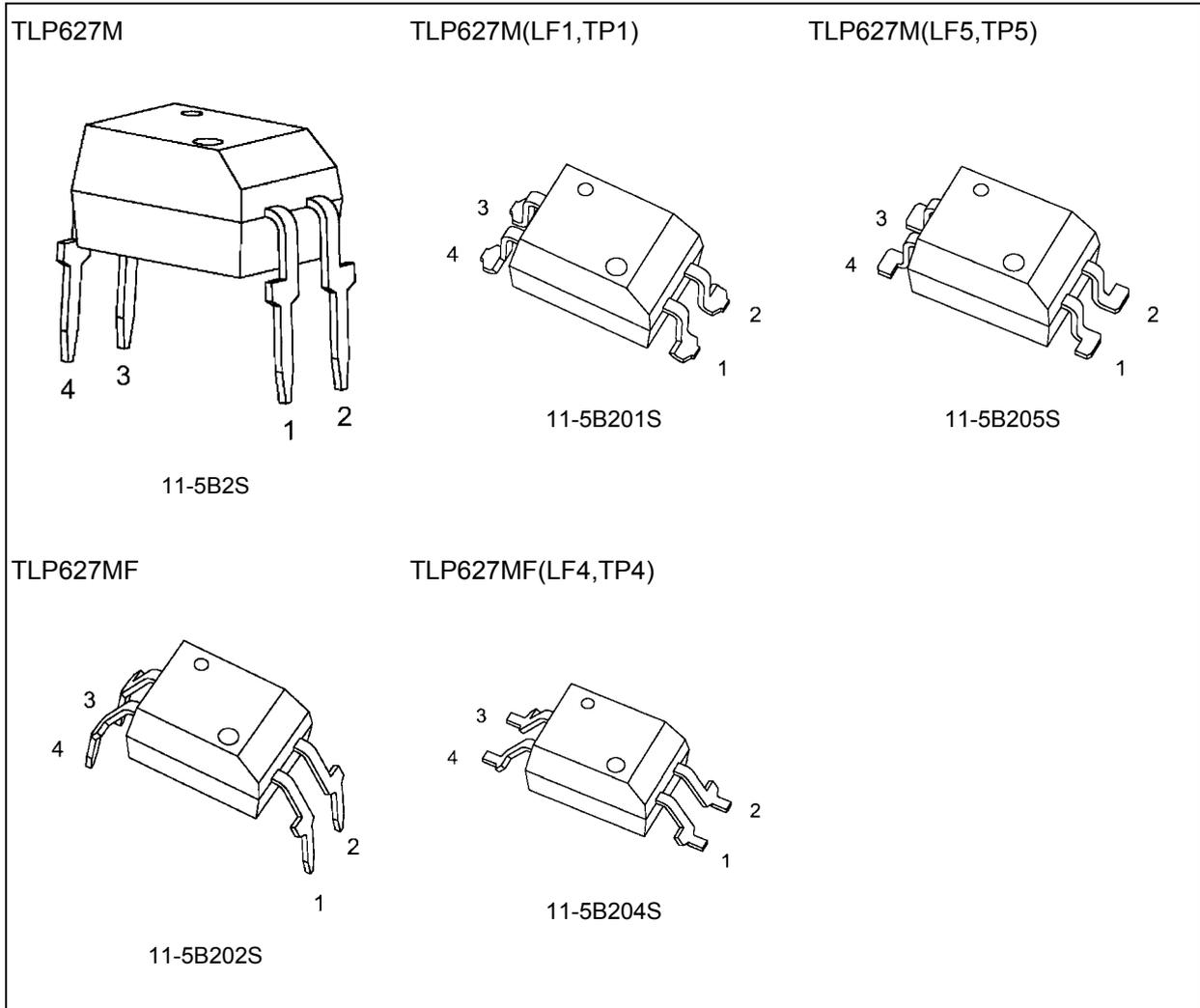


Note 1: When a VDE approved type is needed, please designate the **Option (D4)**.

Start of commercial production

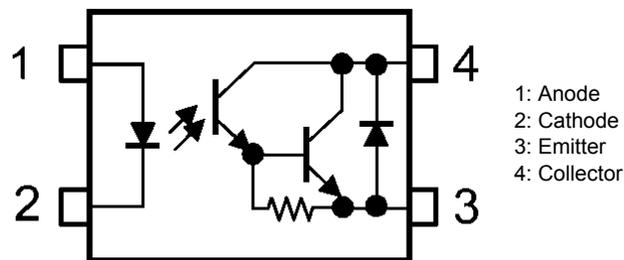
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### 4. Packaging (Note)



Note: Through-hole type: TLP627M, TLP627MF  
 Lead forming option: (LF1), (LF4), (LF5)  
 Taping option: (TP1), (TP4), (TP5)

### 5. Pin Assignment



1: Anode  
 2: Cathode  
 3: Emitter  
 4: Collector

### 6. Mechanical Parameters

Characteristics	7.62 mm pitch TLP627M type (Min)	10.16 mm pitch TLP627MF type (Min)	Unit
Creepage distances	7.0	8.0	mm
Clearance	7.0	8.0	
Internal isolation thickness	0.4	0.4	

### 7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	$I_F$		50	mA
	Input forward current derating ( $T_a \geq 90\text{ }^\circ\text{C}$ )	$\Delta I_F/\Delta T_a$		-1.42	mA/°C
	Input forward current (pulsed)	$I_{FP}$	(Note 1)	1	A
	Input reverse voltage	$V_R$		5	V
	Input power dissipation	$P_D$		100	mW
	Input power dissipation derating ( $T_a \geq 90\text{ }^\circ\text{C}$ )	$\Delta P_D/\Delta T_a$		-2.85	mW/°C
	Junction temperature	$T_j$		125	°C
Detector	Collector-emitter voltage	$V_{CEO}$		300	V
	Emitter-collector voltage	$V_{ECO}$		0.3	V
	Collector current	$I_C$		150	mA
	Collector power dissipation	$P_C$		150	mW
	Collector power dissipation derating ( $T_a \geq 25\text{ }^\circ\text{C}$ )	$\Delta P_C/\Delta T_a$		-1.5	mW/°C
	Junction temperature	$T_j$		125	°C
Common	Operating temperature	$T_{opr}$		-55 to 110	°C
	Storage temperature	$T_{stg}$		-55 to 125	°C
	Lead soldering temperature (10 s)	$T_{sol}$		260	°C
	Total power dissipation	$P_T$		250	mW
	Total power dissipation derating ( $T_a \geq 25\text{ }^\circ\text{C}$ )	$\Delta P_T/\Delta T_a$		-2.5	mW/°C
	Isolation voltage (AC, 60 s, R.H. $\leq 60\%$ )	$BV_S$	(Note 2)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: Pulse width (PW)  $\leq 0.1\text{ ms}$ ,  $f = 100\text{ Hz}$

Note 2: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

### 8. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	$V_F$		$I_F = 10\text{ mA}$	1.1	1.25	1.4	V
	Input reverse current	$I_R$		$V_R = 5\text{ V}$	—	—	10	$\mu\text{A}$
	Input capacitance	$C_t$		$V = 0\text{ V}$ , $f = 1\text{ MHz}$	—	30	—	pF
Detector	Collector-emitter breakdown voltage	$V_{(BR)CEO}$		$I_C = 0.1\text{ mA}$	300	—	—	V
	Emitter-collector breakdown voltage	$V_{(BR)ECO}$		$I_E = 0.1\text{ mA}$	0.3	—	—	V
	Dark Current	$I_{DARK}$		$V_{CE} = 200\text{ V}$	—	0.002	0.2	$\mu\text{A}$
				$V_{CE} = 200\text{ V}$ , $T_a = 85\text{ }^\circ\text{C}$	—	—	20	
Collector-emitter capacitance	$C_{CE}$		$V = 0\text{ V}$ , $f = 1\text{ MHz}$	—	900	—	pF	

### 9. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	$I_C/I_F$		$I_F = 1\text{ mA}$ , $V_{CE} = 1\text{ V}$	1000	6000	—	%
Saturated current transfer ratio	$I_C/I_{F(sat)}$		$I_F = 10\text{ mA}$ , $V_{CE} = 1\text{ V}$	500	—	—	%
Collector-emitter saturation voltage	$V_{CE(sat)}$		$I_C = 10\text{ mA}$ , $I_F = 1\text{ mA}$	—	—	1.0	V
			$I_C = 100\text{ mA}$ , $I_F = 10\text{ mA}$	0.3	—	1.2	
OFF-state collector current	$I_{C(off)}$		$V_F = 0.7\text{ V}$ , $V_{CE} = 200\text{ V}$	—	—	20	$\mu\text{A}$

### 10. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	$C_S$	(Note 1)	$V_S = 0\text{ V}$ , $f = 1\text{ MHz}$	—	0.6	—	pF
Isolation resistance	$R_S$	(Note 1)	$V_S = 500\text{ V}$ , R.H. $\leq 60\%$	$1 \times 10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$BV_S$	(Note 1)	AC, 60 s	5000	—	—	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

### 11. Switching Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$ )

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Rise time	$t_r$		$V_{CC} = 10\text{ V}$ , $I_C = 10\text{ mA}$ , $R_L = 100\ \Omega$	—	60	—	$\mu\text{s}$
Fall time	$t_f$			—	30	—	
Turn-on time	$t_{on}$			—	110	—	
Turn-off time	$t_{off}$			—	30	—	
Turn-on time	$t_{on}$		See Fig. 11.1. $R_L = 180\ \Omega$ , $V_{CC} = 10\text{ V}$ , $I_F = 16\text{ mA}$	—	2	—	
Storage time	$t_s$			—	25	—	
Turn-off time	$t_{off}$			—	80	—	

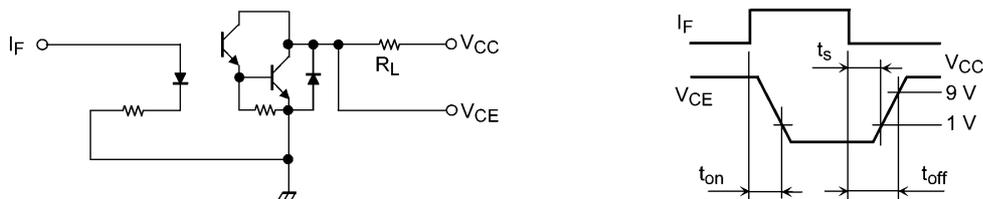
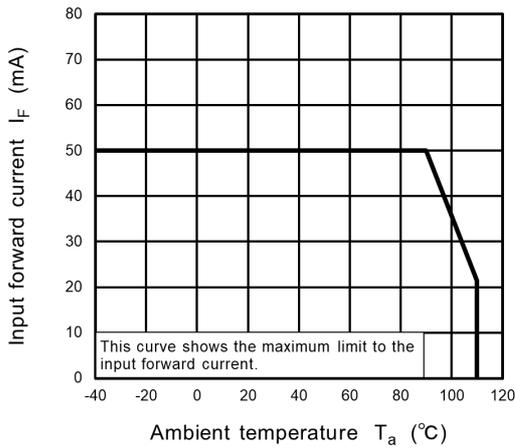
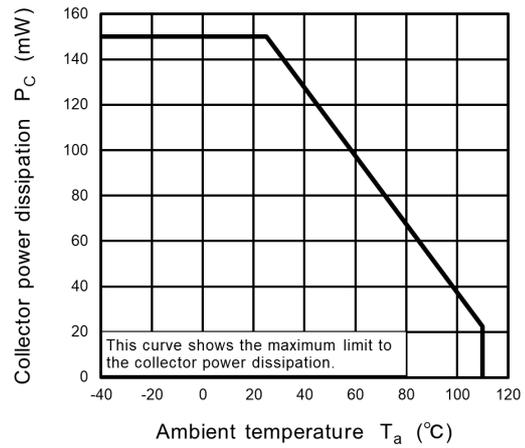


Fig. 11.1 Switching Time Test Circuit and Waveform

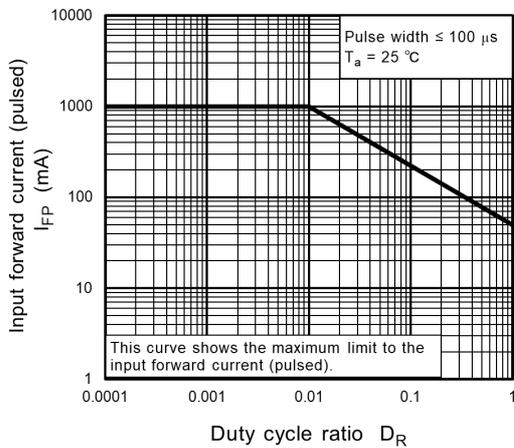
### 12. Characteristics Curves (Note)



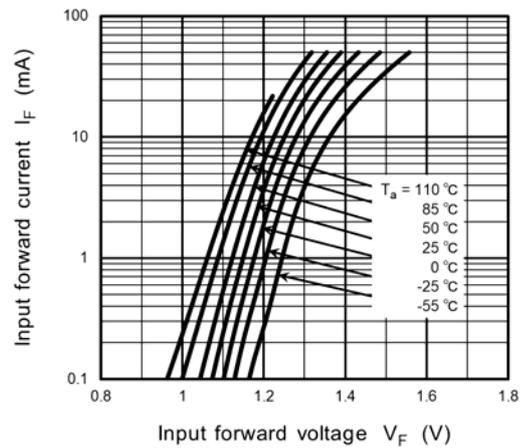
**Fig. 12.1  $I_F - T_a$**



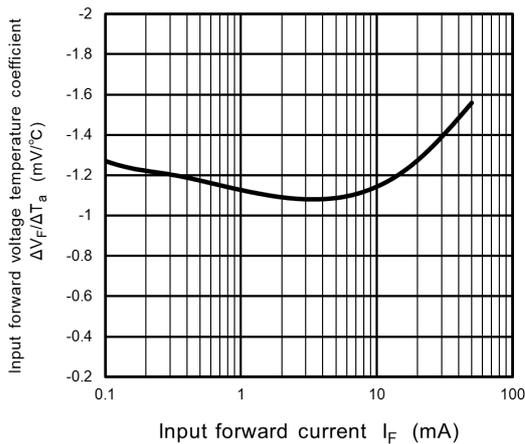
**Fig. 12.2  $P_C - T_a$**



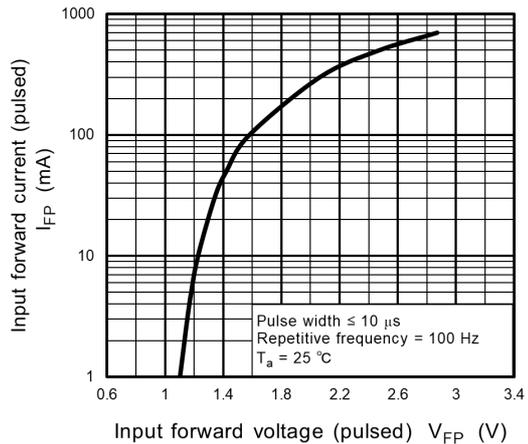
**Fig. 12.3  $I_{FP} - D_R$**



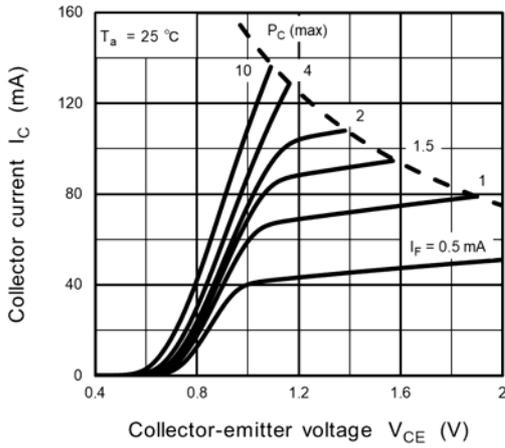
**Fig. 12.4  $I_F - V_F$**



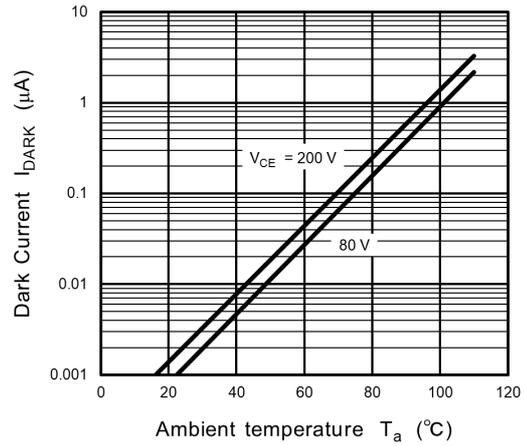
**Fig. 12.5  $\Delta V_F/\Delta T_a - I_F$**



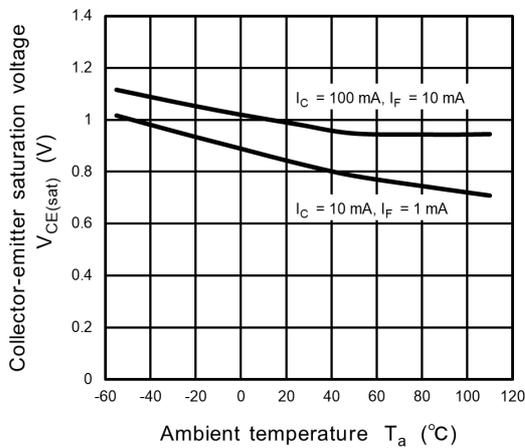
**Fig. 12.6  $I_{FP} - V_{FP}$**



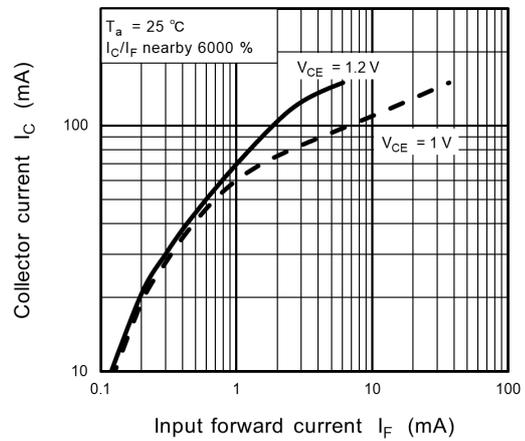
**Fig. 12.7  $I_C - V_{CE}$**



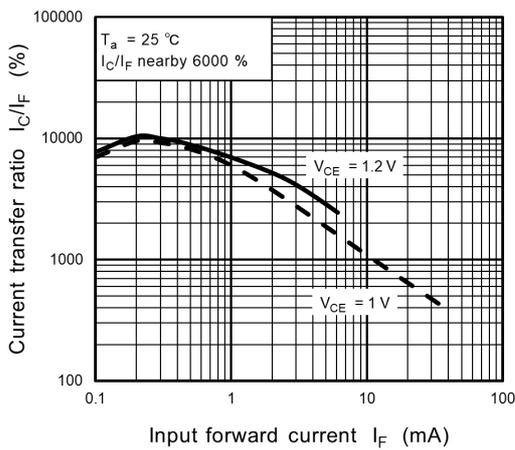
**Fig. 12.8  $I_{DARK} - T_a$**



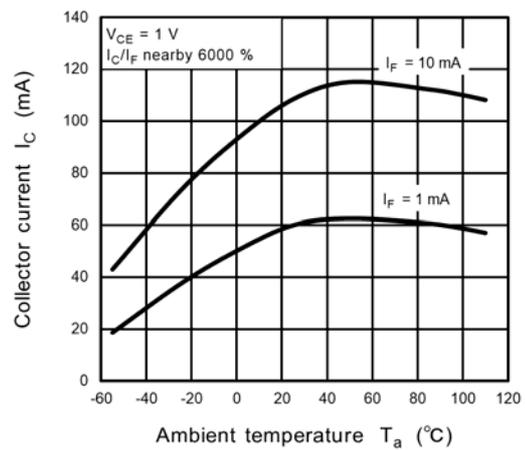
**Fig. 12.9  $V_{CE(sat)} - T_a$**



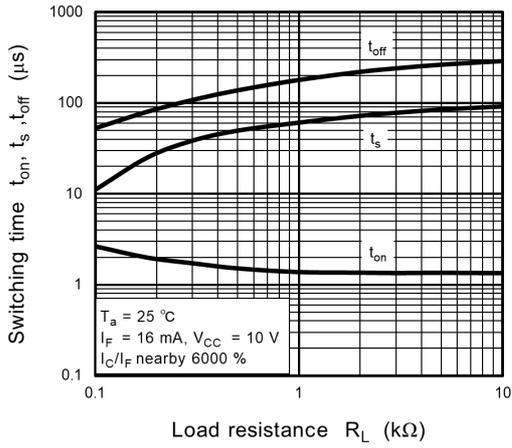
**Fig. 12.10  $I_C - I_F$**



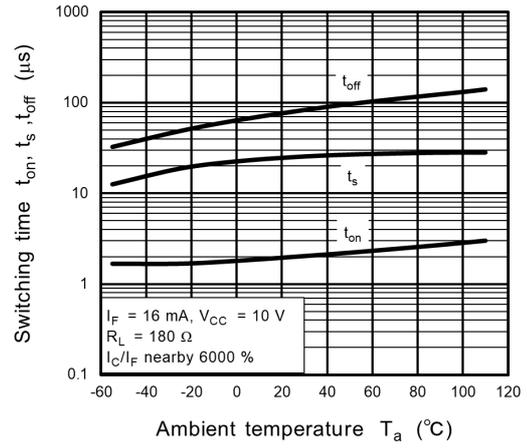
**Fig. 12.11  $I_C/I_F - I_F$**



**Fig. 12.12  $I_C - T_a$**



**Fig. 12.13 Switching Time - R<sub>L</sub>**



**Fig. 12.14 Switching Time - T<sub>a</sub>**

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### 13. Soldering and Storage

#### 13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

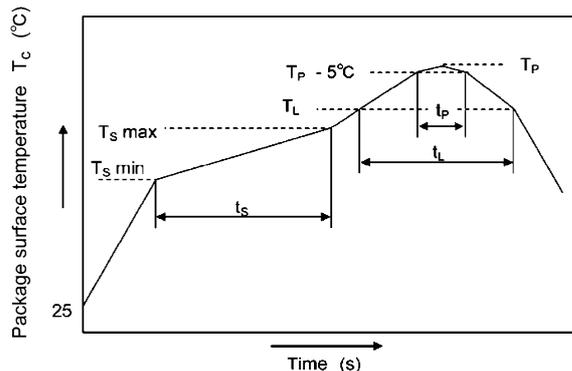
- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	$T_S$	150	200	°C
Preheat time	$t_S$	60	120	s
Ramp-up rate ( $T_L$ to $T_P$ )			3	°C/s
Liquidus temperature	$T_L$	217		°C
Time above $T_L$	$t_L$	60	150	s
Peak temperature	$T_P$		260	°C
Time during which $T_c$ is between ( $T_P - 5$ ) and $T_P$	$t_P$		30	s
Ramp-down rate ( $T_P$ to $T_L$ )			6	°C/s

**An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used**

- When using soldering flow  
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.  
Mounting condition of 260 °C within 10 seconds is recommended.  
Flow soldering must be performed once.
- When using soldering Iron  
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C  
Heating by soldering iron must be done only once per lead.

#### 13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

### 14. Marking (Note)

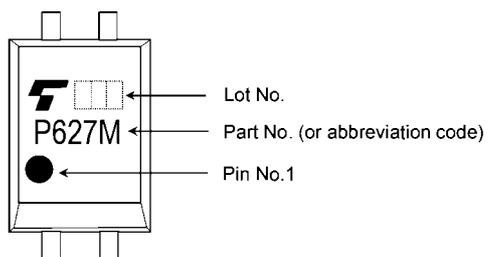


Fig. 14.1 Marking example of TLP627M

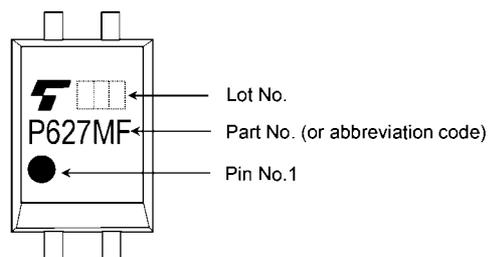


Fig. 14.2 Marking example of TLP627MF

Note: A different marking is used for photocouplers that have been qualified according to option (D4) of EN 60747. See Fig.15.4 and Fig.15.5.

### 15. EN 60747-5-5 Option (D4) Specification

- Part number: TLP627M, TLP627MF (**Note 1**)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN 60747.

Example: TLP627M(D4-TP1,E)

D4: EN 60747 option

TP1: Tape type

E: [[G]]/RoHS COMPATIBLE (**Note 2**)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP627M(D4-TP1,E) → TLP627M

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description		Symbol	Rating	Unit
Application classification				
for rated mains voltage $\leq 600$ Vrms			I-IV	—
for rated mains voltage $\leq 1000$ Vrms			I-III	
Climatic classification			55 / 110 / 21	—
Pollution degree			2	—
Maximum operating insulation voltage	TLPxxxx type	VIORM	890	Vpeak
	TLPxxxxF type		1140	
Input to output test voltage, Method A $V_{pr} = 1.6 \times VIORM$ , type and sample test $t_p = 10$ s, partial discharge $< 5$ pC	TLPxxxx type	Vpr	1424	Vpeak
	TLPxxxxF type		1824	
Input to output test voltage, Method B $V_{pr} = 1.875 \times VIORM$ , 100 % production test $t_p = 1$ s, partial discharge $< 5$ pC	TLPxxxx type	Vpr	1670	Vpeak
	TLPxxxxF type		2140	
Highest permissible overvoltage (transient overvoltage, $t_{pr} = 60$ s)		VTR	8000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve)				
current (input current $I_F$ , $P_{SO} = 0$ )		Isi	400	mA
power (output or total power dissipation)		Pso	700	mW
temperature		Ts	150	°C
Insulation resistance	$V_{IO} = 500$ V, $T_a = 25$ °C	Rsi	$\geq 10^{12}$	$\Omega$
	$V_{IO} = 500$ V, $T_a = 100$ °C		$\geq 10^{11}$	
	$V_{IO} = 500$ V, $T_a = T_s$		$\geq 10^9$	

Fig. 15.1 EN 60747 Insulation Characteristics

		 7.62 mm pitch TLPxxx type	 10.16 mm pitch TLPxxxF type
Minimum creepage distance	Cr	7.0 mm	8.0 mm
Minimum clearance	Cl	7.0 mm	8.0 mm
Minimum insulation thickness	ti	0.4 mm	
Comparative tracking index	CTI	175	

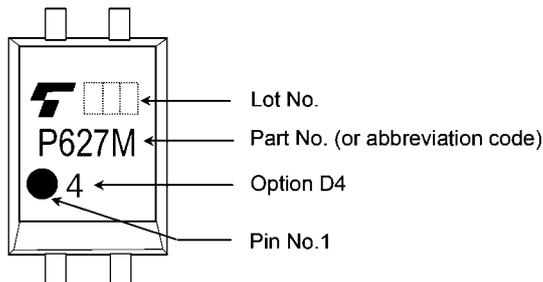
**Fig. 15.2 Insulation Related Specifications (Note)**

Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e.g., at a standard distance between soldering eye centers of 7.5 mm). If this is not permissible, the user shall take suitable measures.

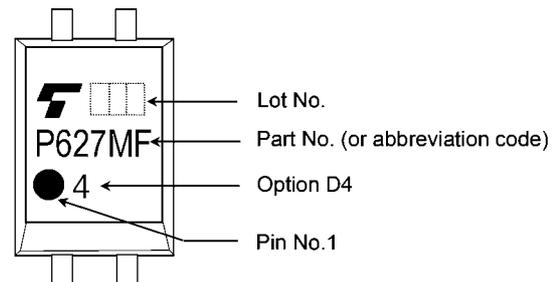
Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



**Fig. 15.3 Marking on packing for EN 60747**



**Fig. 15.4 Marking Example of TLP627M(Note)**



**Fig. 15.5 Marking Example of TLP627MF(Note)**

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN 60747.

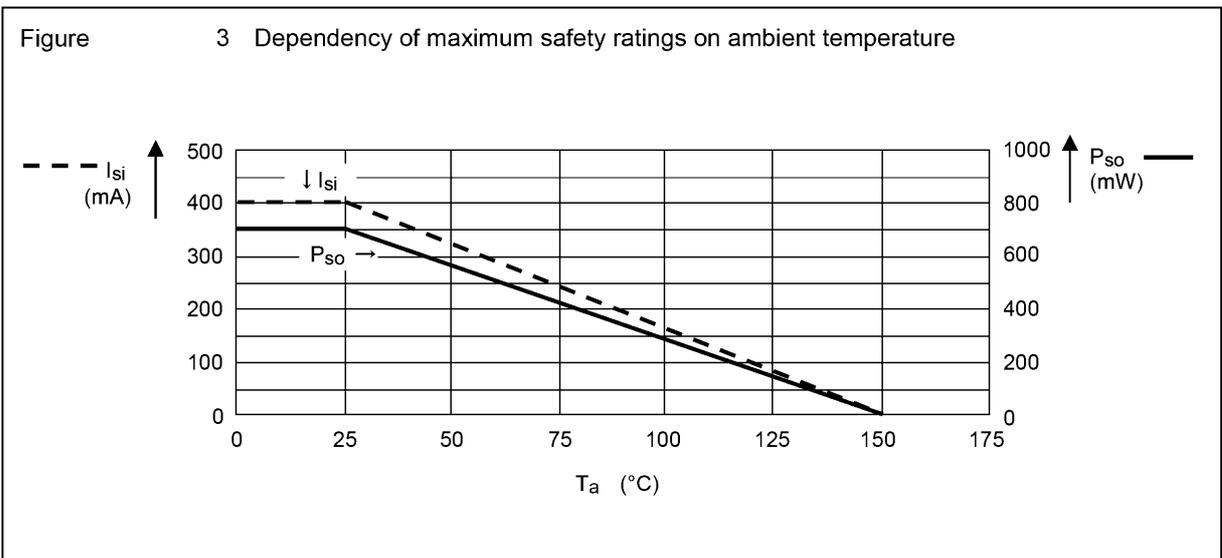
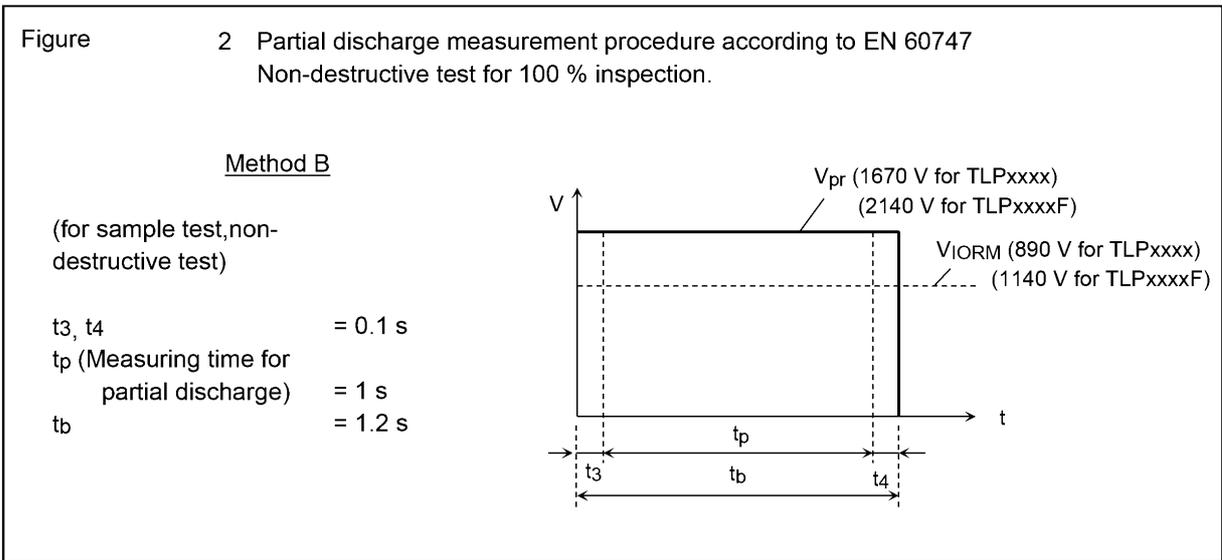
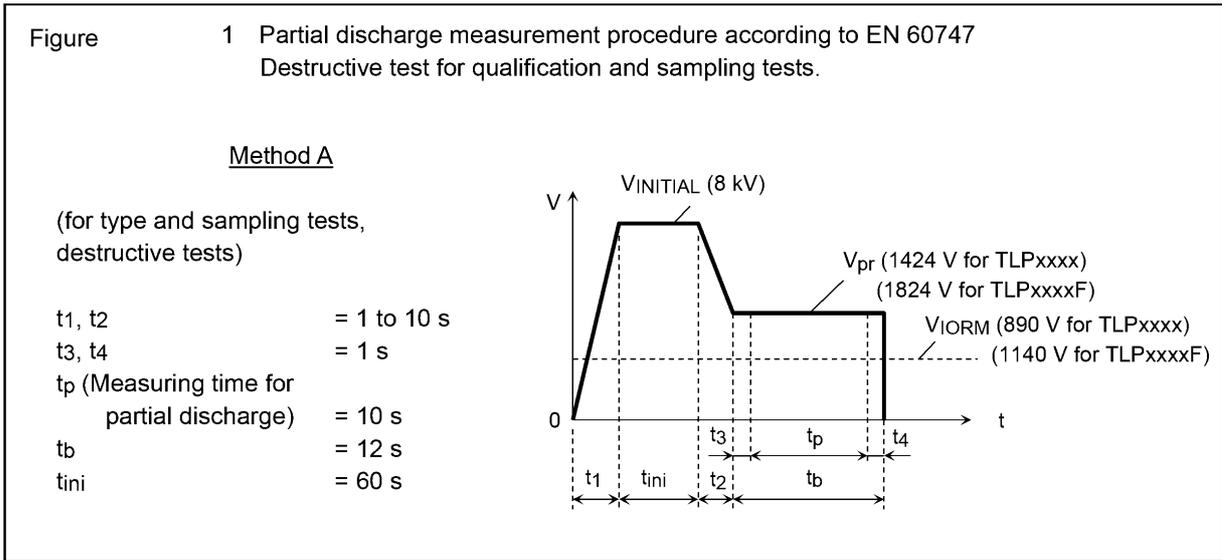
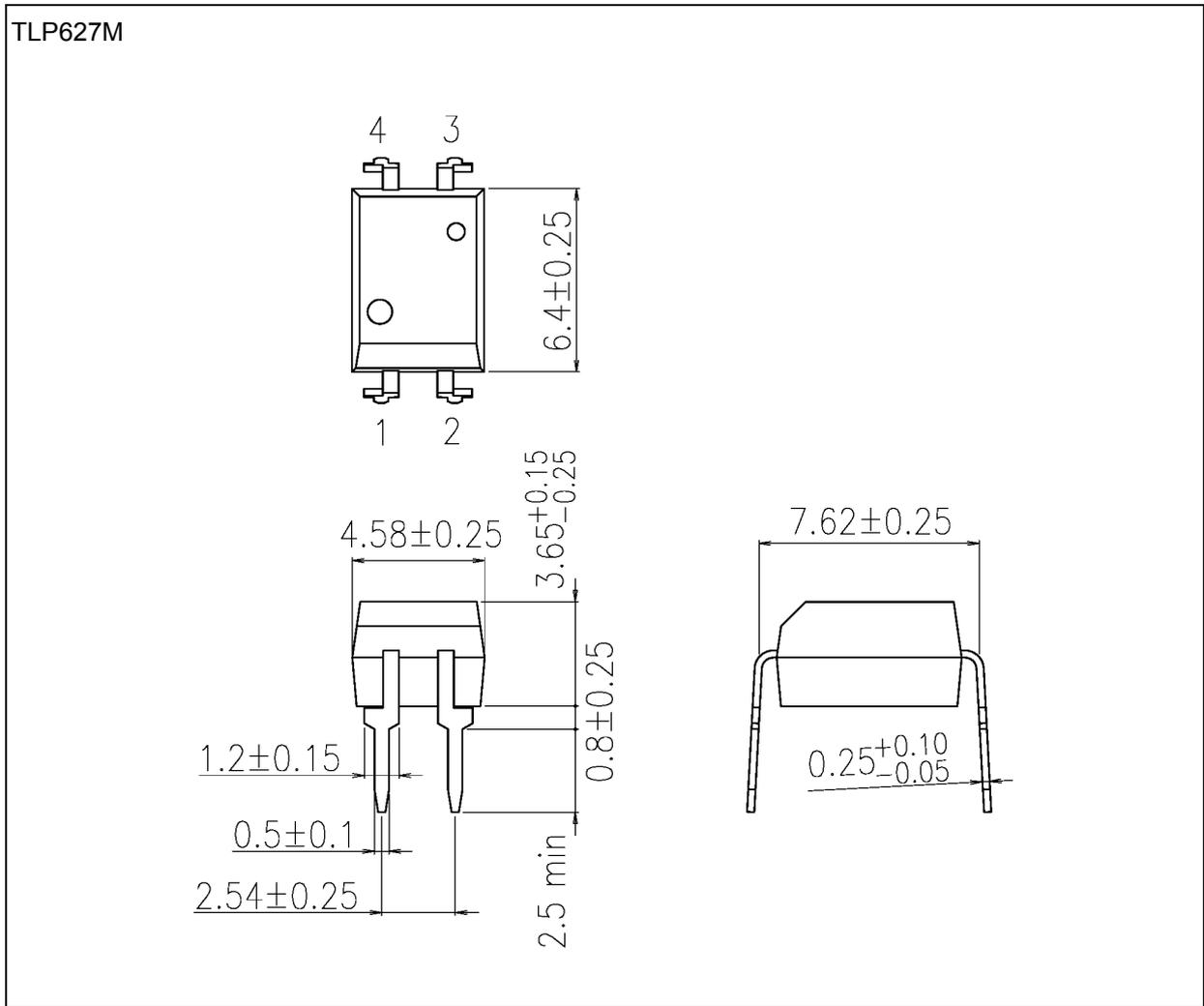


Fig. 15.6 Measurement Procedure

## Package Dimensions

Unit: mm

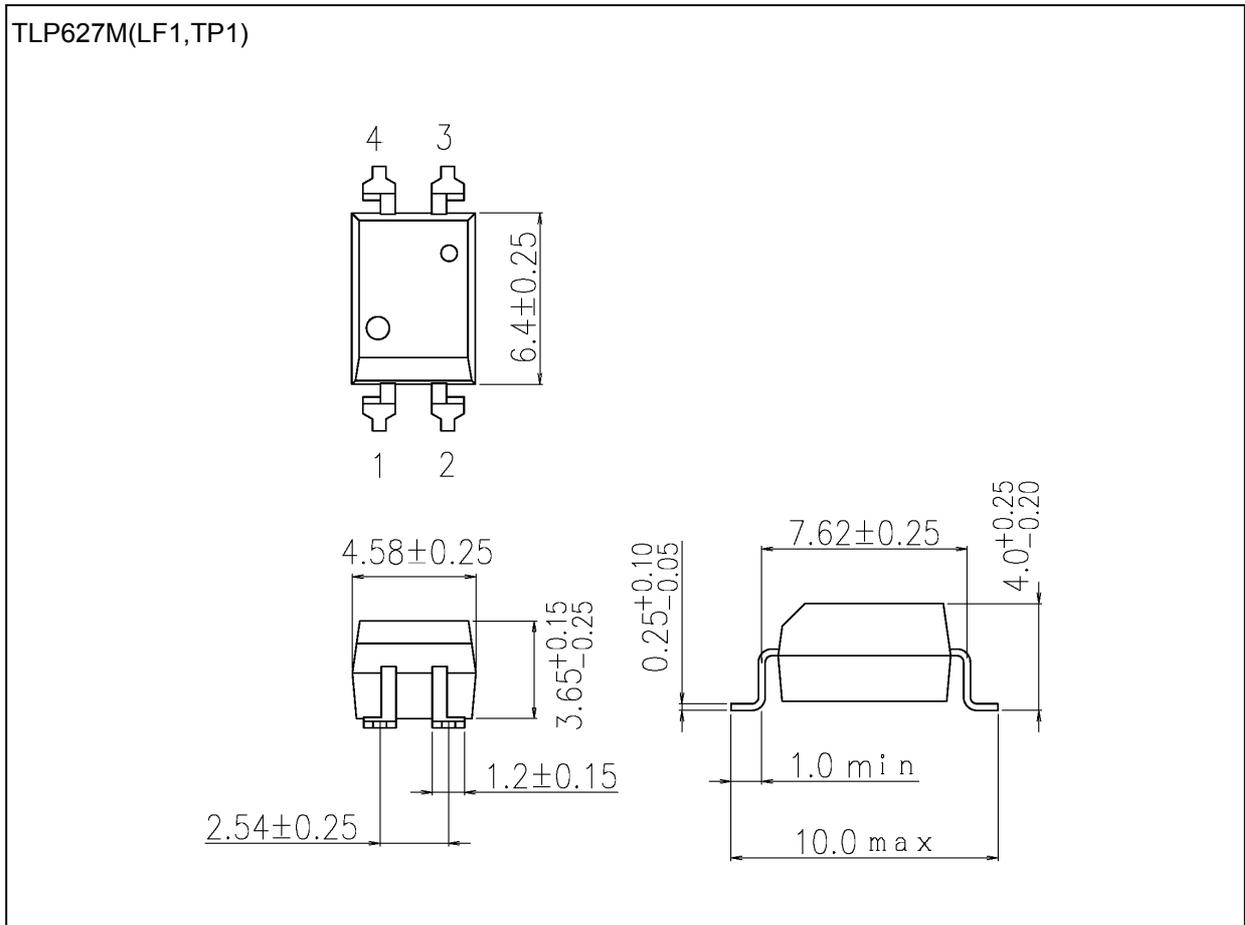


Weight: 0.24 g (typ.)

Package Name(s)
TOSHIBA: 11-5B2S

## Package Dimensions

Unit: mm

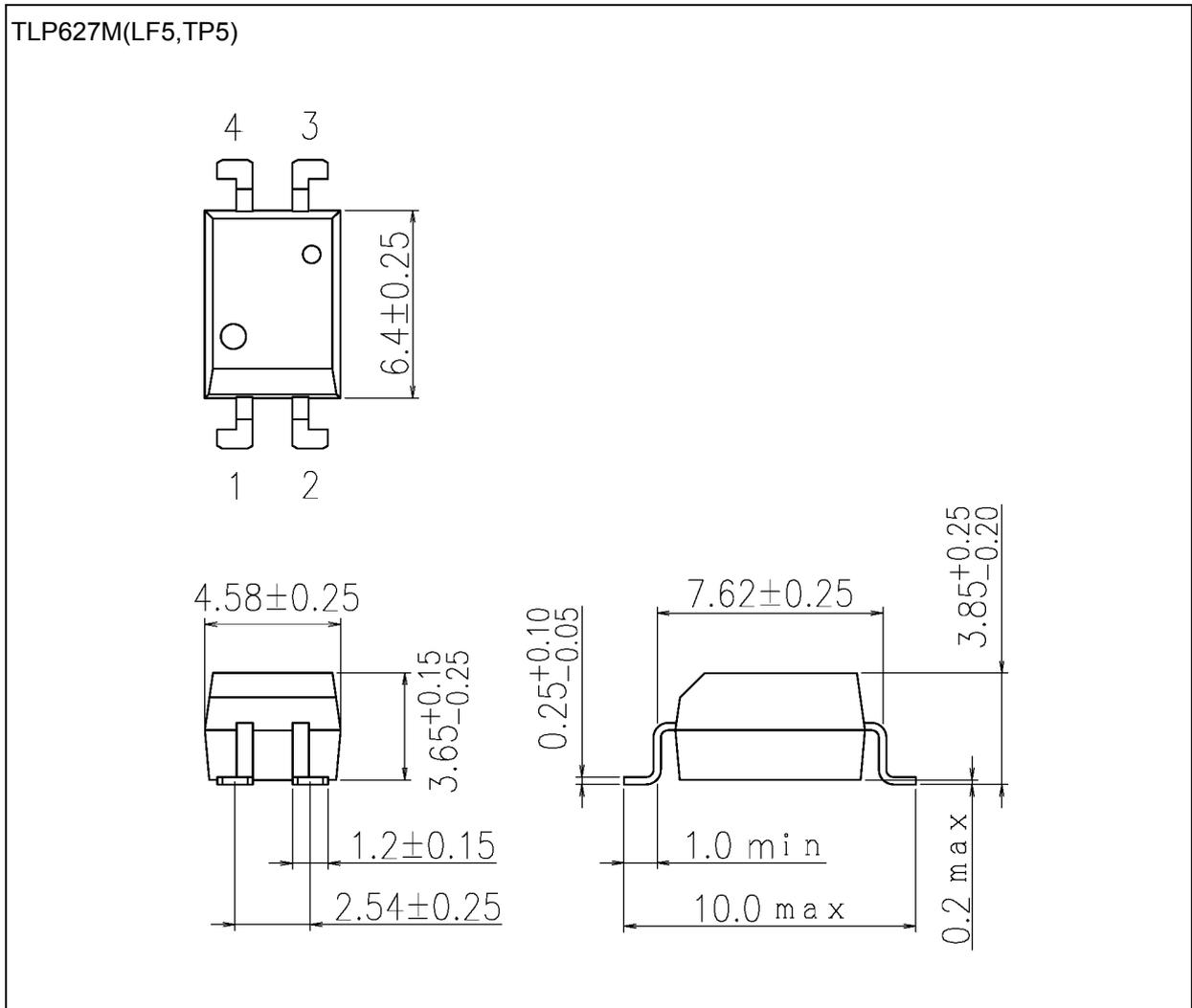


Weight: 0.24 g (typ.)

Package Name(s)
TOSHIBA: 11-5B201S

## Package Dimensions

Unit: mm

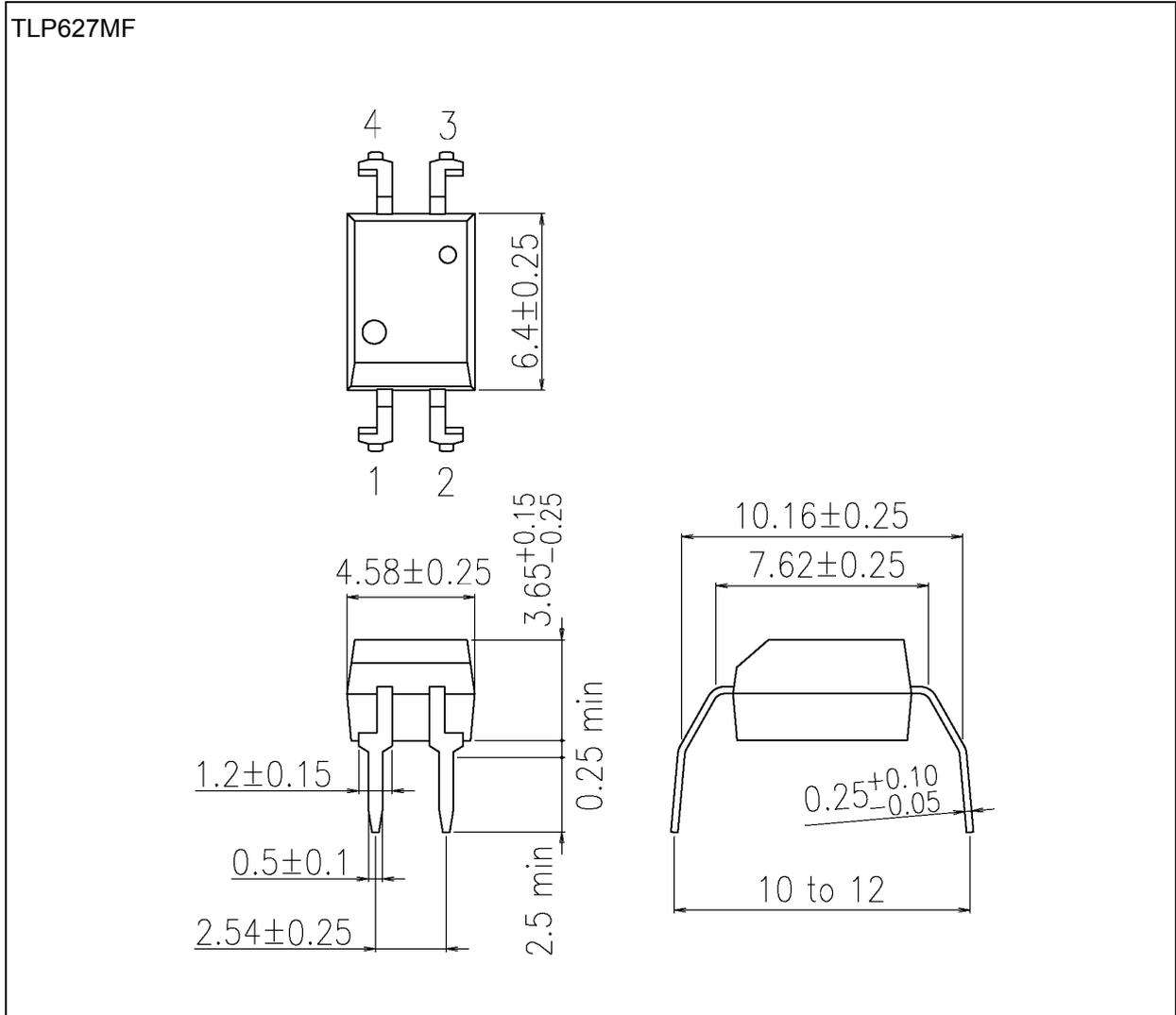


Weight: 0.24 g (typ.)

Package Name(s)
TOSHIBA: 11-5B205S

## Package Dimensions

Unit: mm

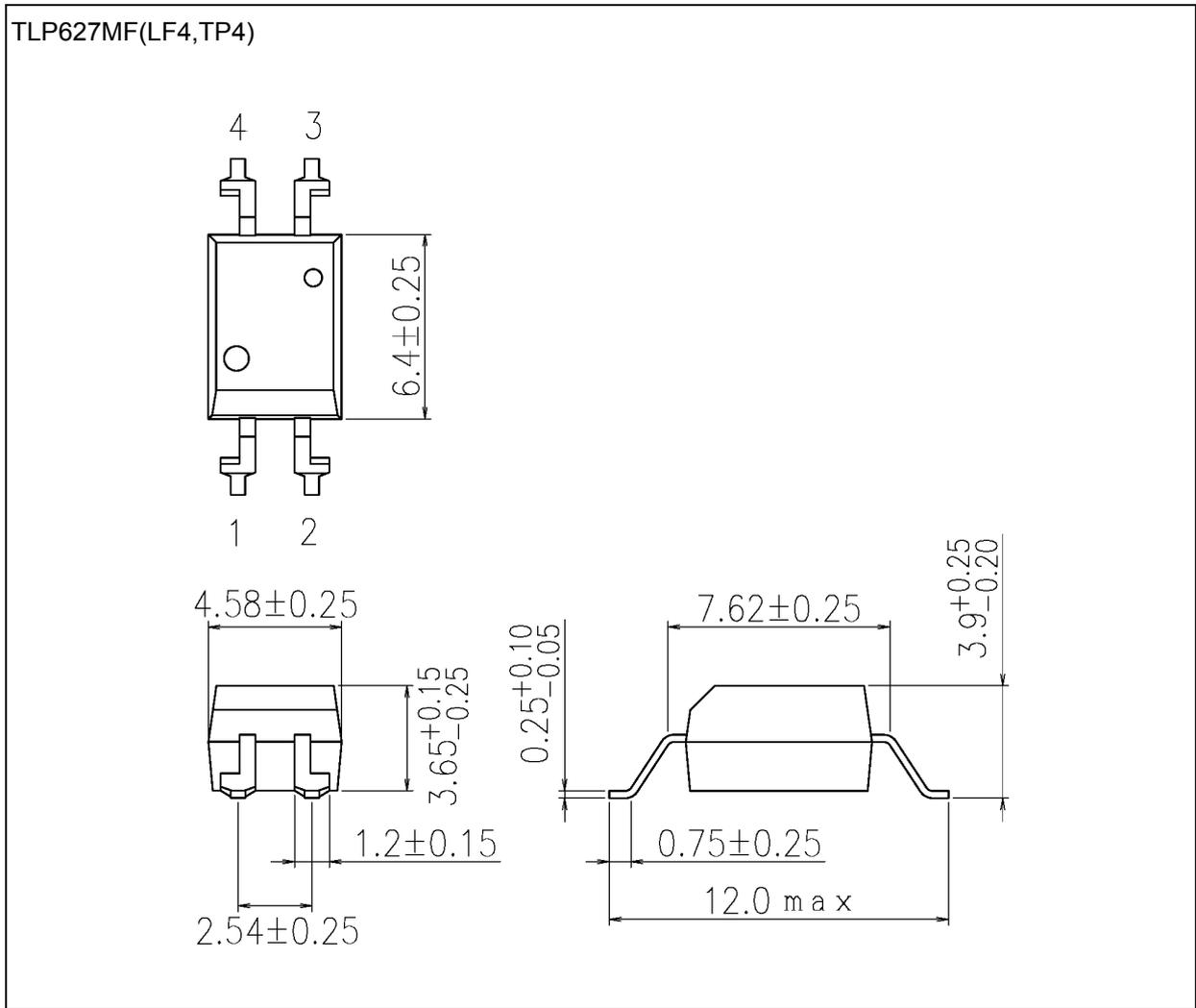


Weight: 0.24 g (typ.)

Package Name(s)
TOSHIBA: 11-5B202S

## Package Dimensions

Unit: mm



Weight: 0.24 g (typ.)

Package Name(s)
TOSHIBA: 11-5B204S

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